



102627532

To the Honorable Assistant Secretary and Clerk thereof.

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1. Name of conveying party(ies): 12-15-03  
Shinichi NOMOTO and Takashi NAUCHI

2. Name and address of receiving party(ies):  
Name: SENJU METAL INDUSTRY CO., LTD.  
Street Address: 23, Senju Hashido-cho, Adachi-ku, Tokyo, Japan

Additional name(s) of conveying party(ies) attached? No  
3. Nature of conveyance:  
 Assignment                       Merger  
 Security Agreement             Change of Name  
 Other \_\_\_\_\_  
Execution Date: December 1, 2003

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4. Application number(s) or patent number(s): 1 5734234

If this document is being filed together with a new application, the execution date of the application is: December 1, 2003

A. Patent Application No.(s)  
B. Patent No.(s)  
, issued  
Additional numbers attached? No

5. Name and address of party to whom correspondence concerning document should be mailed:  
Name: WENDEROTH, LIND & PONACK, L.L.P.  
Attn: Michael S. Huppert, Esq.  
Street Address: 2033 K Street, N.W., Suite 800  
City: Washington, State: DC ZIP: 20006-1021

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41) . . . . . \$ 40.00  
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*To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.*

Michael S. Huppert, Reg. No. 40,268  
Name of Person Signing

*Michael S. Huppert*  
Signature

December 15, 2003  
Date

Total number of pages including cover sheet: 3

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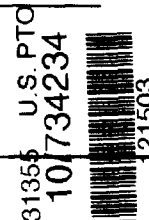
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12/16/2003 ZJUHA1 00000051 10734234

FD-8021

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# ASSIGNMENT

In consideration of the sum of One Dollar (\$1.00) and other good and valuable consideration paid to each of the undersigned

Shinichi NOMOTO and Takashi NAUCHI

Insert Name(s)  
of Inventor(s)

Insert Name(s)  
of Assignee(s)

Address

the undersigned hereby sell(s) and assign(s) to

SENJU METAL INDUSTRY CO., LTD.

of 23, Senju Hashido-cho, Adachi-ku, Tokyo, Japan

(hereinafter designated as the Assignee) the entire right, title and interest for the United States as defined in 35 USC 100, in the invention known as

APPARATUS FOR ALIGNING AND DISPENSING SOLDER COLUMNS IN AN ARRAY

Title of  
Invention

for which an application for patent in the United States has been executed by the undersigned on

Date of Signing  
Application

December 1, 2003

The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation, division or reissue thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such interference.

The undersigned agree(s) to execute all papers and documents and perform any act which may be necessary in connection with claims or provisions of the International Convention for Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent to the Assignee.

The undersigned hereby authorize(s) and request(s) the Commissioner of Patents to issue any and all Letters Patents of the United States resulting from said application or any division or divisions or continuing or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

The undersigned hereby grant(s) the firm of WENDEROTH, LIND & PONACK, L.L.P., 2033 K Street, N.W., Suite 800, Washington, DC 20006, the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent Office for recordation of this document.

In witness whereof, executed by the undersigned on the date(s) opposite the undersigned name(s).

Date December 1, 2003, Name of Inventor Shinichi Nomoto Shinichi NOMOTO  
Date December 1, 2003, Name of Inventor Takashi Nauchi Takashi NAUCHI  
Date \_\_\_\_\_, Name of Inventor \_\_\_\_\_  
Date \_\_\_\_\_, Name of Inventor \_\_\_\_\_  
Date \_\_\_\_\_, Name of Inventor \_\_\_\_\_  
Date \_\_\_\_\_, Name of Inventor \_\_\_\_\_

(This assignment should preferably be acknowledged before a United States Consul. If not, then the execution by the Inventor(s) should be witnessed by at least two witnesses who sign here.)

Witness [Signature]  
Witness [Signature]

### ACKNOWLEDGMENT

\_\_\_\_\_  
\_\_\_\_\_ } SS

This \_\_\_\_\_ day of \_\_\_\_\_, 19\_\_\_\_\_, before me  
personally came the above-named \_\_\_\_\_

to me personally known as the individual(s) who executed the foregoing assignment, who did acknowledge to me that he (they) executed the same of his (their) own free will for the purposes therein set forth.

SEAL \_\_\_\_\_ Official Signature  
\_\_\_\_\_ Official Title

The above application may be more particularly identified as follows:

U.S. Application Serial No. \_\_\_\_\_ Filing Date December 15, 2003  
Applicant Reference No. ME:OH:NF, FP/S-16-84US Atty. Docket No. 2003-1810A  
Title of Invention \_\_\_\_\_